

(0.635 mm) .025"

MIS SERIES

MIXED TECHNOLOGY SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MIS

- Insulator Material:** Liquid Crystal Polymer
- Contact Material:** Phosphor Bronze
- Plating:** Au or Sn over 50 μm (1.27 μm) Ni
- Operating Temp Range:** -55 °C to +125 °C
- Voltage Rating:** 275 VAC
- Max Cycles:** 100
- RoHS Compliant:** Yes

Board Mates: MIT

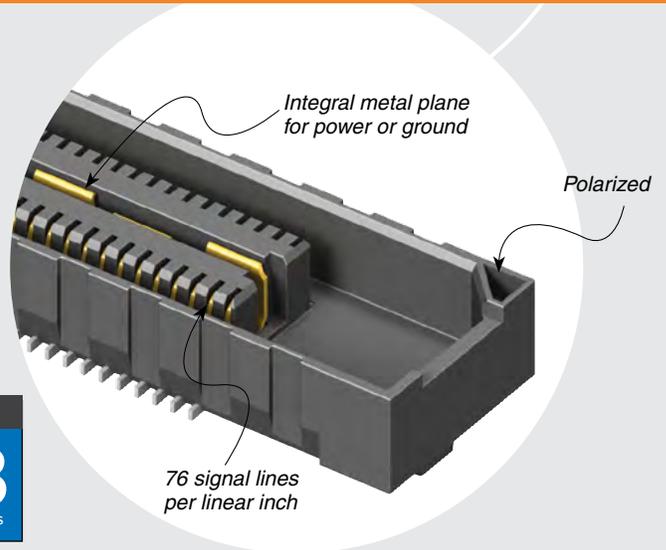
Standoffs: SO



HIGH-SPEED CHANNEL PERFORMANCE

MIT/MIS @ 5 mm Mated Stack Height
 Rating based on Samtec reference channel
 For full SI performance data visit Samtec.com or contact SIG@samtec.com

28
Gbps



PROCESSING

- Lead-Free Solderable:** Yes
- SMT Lead Coplanarity:** (0.10 mm) .004" max (019-057)
- Board Stacking:** For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

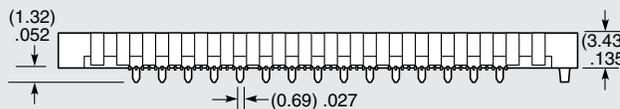
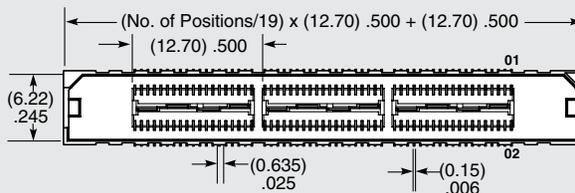
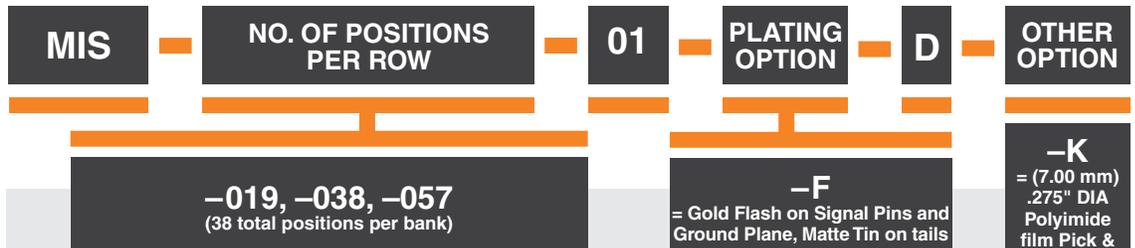
For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

ALSO AVAILABLE (MOQ Required)

- 11 mm, 16 mm, 18.75 mm and 22 mm stack height
 - 30 μm (0.76 μm) Gold
 - Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
 - 76, 95, 114 and 133 positions per row
- Contact Samtec.



- F**
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails
- L**
= 10 μm (0.25 μm) Gold on Signal Pins and Ground Plane, Matte Tin on tails
- C***
= Electro-Polished Selective 50 μm (1.27 μm) min Au over 150 μm (3.81 μm) Ni on Signal Pins in contact area, 10 μm (0.25 μm) min Au over 50 μm (1.27 μm) Ni on Ground Plane in contact area, Matte Tin over 50 μm (1.27 μm) min Ni on all solder tails

- K**
= (7.00 mm) .275" DIA Polyimide film Pick & Place Pad
- TR**
= Tape & Reel

Note: Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

MATED HEIGHT*		
MIS LEAD STYLE	MIT LEAD STYLE	
	-01	-02
-01	(5.00) .197	(8.00) .315

*Processing conditions will affect mated height. See SO Series for board space tolerances.